

LISTING OF THE CLAIMS:

Claims 1-30 (Cancelled).

31. (Previously Presented) Stamp device for printing a pattern on a surface of a substrate, said device having a two-sided rigid carrier layer providing on a first side thereof a patterned layer made of a first material and being combined on a second side opposite said first side with a soft layer made of a softer material than said first material, said patterned layer being stretched to selectively compensate for thermal, chemical, and mechanically induced deformation of said patterned layer to result in accurate prints; said carrier layer describes an x-y-plane in which said carrier layer is rigid and said carrier layer is flexible in a direction perpendicular to said x-y-plane; said patterned layer providing at least one force transducer zone arranged proximate the margin of said patterned layer for monitoring a force induced load acting between said stamp and said substrate.
32. (Previously Presented) Stamp device according to claim 31, wherein said force transducer zone provides a patterned structure in said patterned layer along the stamp margin surrounding at least an unencumbered area, and proximate said unencumbered area there are provided contoured structures in said patterned layer which bound the unencumbered area of said layer in at least one direction.

33. (Previously Presented) Stamp device according to claim 31, wherein said force transducer zone provides a patterned configuration surrounding at least an unencumbered area; and separating means which divide said unencumbered area into at least two unencumbered surface sections.
34. (Previously Presented) Stamp device according to claim 31, wherein said carrier layer is selected from a material consisting of a metal foil, thin glass or quartz substrate.
35. (Previously Amended) Stamp device according to claim 32, wherein said soft layer is of a thickness which is greater than the combined thickness of said patterned layer and of a stamp layer.
36. (Previously Presented) Stamp device according to claim 35, wherein said structure depths in said patterned layer are less than the thickness of said soft layer.
37. (Previously Presented) Stamp device according to claim 31, wherein said soft layer includes a backside and said stamp device comprises a press for directing a force against said backside for contacting said patterned layer with said surface of said substrate.
38. (Previously Presented) Stamp device according to claim 37, wherein said press comprises a roller element forming a cylindrical press having an at least partially cylindrical surface.

Claims 39-47 (Cancelled).

48. (Previously Presented) Stamp device for printing a pattern on a surface of substrate, said device having two-sided rigid carrier layer providing on a first side thereof a patterned layer made of a first material and being combined on a second side opposite said first side with a soft layer made of a softer material than said first material, said patterned layer being stretched to selectively compensate for thermal, chemical and mechanically induced deformation of said patterned layer to result in accurate prints;
- said carrier layer describes an x-y-plane in which said carrier layer is rigid and said carrier layer is flexible in a direction perpendicular to said x-y-plane, wherein said patterned layer includes patterned structures for contacting said surface of said substrate and the first material of said patterned layer is at least partially omitted so as to form at least one recess and wherein at least one passage channel breaks through said carrier layer into said at least one recess for creating a fluidic or gas network between said surface of said substrate and said stamp device.
49. (Previously Presented) Stamp device according to claim 48, wherein there are provided at least two said passage channels comprising an inflow channel and an outflow channel for said fluidic or gas network.
50. (Currently Amended) Stamp device according to claim 48, wherein at least two layers of said fluidic or gas network are stacked on top of each other and having communicating [[said]] passage channels in said at least one recess in said layers to allow formations of

multidimensional networks providing access to a multitude of substances at a multitude of locations without level intersections.

51. (Currently Amended) Stamp device according to claim ~~48 or~~ 52,

wherein unencumbered areas on said patterned layer are connected to a closed further fluidic network and are pressurized through said at least one passage channel to prevent said areas from sagging and contacting said substrate upon the applying of a load onto said stamp device.

52. (Currently Amended) Stamp device for printing a pattern on a surface of a substrate, said device having a two-sided rigid carrier layer providing on a first side thereof a patterned layer made of a first material and being combined on a second side opposite said first side with a soft layer made of a softer material than said first material, said patterned layer being stretched to selectively compensate for thermal, chemical and mechanically induced deformation of said patterned layer to result in accurate prints; said carrier layer describes an x-y-plane in which said carrier layer is rigid and said carrier layer is flexible in a direction perpendicular to said x-y-plane, wherein said stamp device forms said patterned layer, and the surface of a ~~substrate comprise~~ said patterned layer comprises self-aligning means providing for an accurate relative positioning relative to ~~said stamp device~~ the substrate during printing of said pattern.

53. (Currently Amended) Stamp device according to claim 52, wherein said self-aligning means comprises ~~lock~~ and key elements ~~[[with]]~~ for engaging lock elements of a constant shape and distance, and said key elements are of variable shape dimensionally smaller than said lock elements and increasingly larger for fitting without any mismatch into said lock elements.
54. (Currently Amended) Stamp device according to claim 53, wherein said ~~lock~~ and key elements have tapered flanks for engaging tapered flanks on said lock elements.
55. (Currently Amended) Stamp device according to claim 53, wherein said ~~lock~~ and key elements are arranged in a row along which said patterned layer and said substrate are brought into contact.
56. (Currently Amended) Stamp device according to claim 53, wherein said patterned layer comprises said key elements ~~and said~~ for engaging lock elements on the surface of said substrate ~~comprises said lock elements~~.

Claims 57 and 58 (Cancelled).

59. (Previously Amended) Stamp device according to claim 31, wherein said force transducer zone provides a patterned structure surrounding at least an area free of structures and proximate said area free of structures there are provided structures which bounds the area free of structures in at least one direction.

60. (Previously Amended) Stamp device according to claim 31, wherein said force transducer zone provides a patterned structure surrounding at least an area free of structures; and linear structures are provided which divide said area free of structures in at least two sections.
61. (Previously Presented) Stamp device according to claim 60, wherein at least two linear structures being arranged perpendicular to each other and dividing said area free of structures at least into three sections.
62. (Previously Amended) Stamp device according to claim 31, wherein said force transducer zone is placed in an area near an edge of said patterned layer.
63. (Previously Amended) Stamp device according to claim 52, wherein said patterned layer provides patterned structures for printing said surface of said substrate, said patterned structures being separated from each other by areas free of structures; and support structures selectively in the form of posts or lines, are provided for preventing said areas free of structures from sagging and contacting said substrate by applying a load onto said stamp device.
64. (Previously Amended) Stamp device according to claim 63, wherein said support structures having maximally the same structure depth as said patterned structures and selectively being of the same material or of a harder material.

65. (Previously Amended) Stamp device according to claim 52, wherein said patterned layer provides patterned structures for printing said surface of said substrate and said patterned structures being separated from each other by areas free of structures and in said areas free of structures the first material of said patterned layer is at least partially omitted forming a recess for preventing said areas free of structures from sagging and contacting said substrate by applying a load onto said stamp device.

66. (Previously Amended) Stamp device according to claim 52, wherein said patterned layer provides patterned structures for contacting said surface of said substrate and said patterned structures being separated from each other by areas free of structures and in said areas of structures the first material of said patterned layer is at least partially omitted forming a recess, and wherein at least one passage channel breaks through said carrier layer into said recess for creating a fluidic or gas network between said surface of said substrate and said stamp.

67. (Previously Amended) Stamp device according to claim 66, wherein at least two passage channels are provided, one inflow channel and an other outflow channel for a fluid or gaseous media.

68. (Previously Amended) Stamp device according to claim 66, wherein at least two layers of said fluidic or gas network are stacked on top of each other to allow formation of multidimensional networks providing access to a multitude of substances at a multitude of locations without level intersections.

Claims 69-74 (Cancelled).

75. (Currently Amended) Stamp device according to claim ~~[[74]]~~ 52, wherein said first material of said patterned layer has a thermal expansion coefficient which is greater than the thermal expansion coefficient of said rigid carrier layer.

76. (Previously Amended) Stamp device according to claim 67,
wherein said areas free of structure and connected to a closed gaseous network are pressurized through said at least two passage channels to prevent those areas from sagging and contacting said substrate by applying a load onto said stamp device.